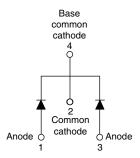


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# HEXFRED® Ultrafast Soft Recovery Diode, 2 x 8 A





PRODUCT SUMMARY						
Package	TO-220AB					
I <sub>F(AV)</sub>	2 x 8 A					
V <sub>R</sub>	600 V					
V <sub>F</sub> at I <sub>F</sub>	1.4 V					
t <sub>rr</sub> typ.	18 ns					
T <sub>J</sub> max.	150 °C					
Diode variation	Common cathode					

#### **FEATURES**

- Ultrafast and ultrasoft recovery
- Very low I<sub>RRM</sub> and Q<sub>rr</sub>
- Designed and qualified according to JEDEC®-JESD47
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>





ROHS
COMPLIANT
HALOGEN
FREE
Available

#### **BENEFITS**

- Reduced RFI and EMI
- Reduced power loss in diode and switching transistor
- Higher frequency operation
- · Reduced snubbing
- · Reduced parts count

#### DESCRIPTION

VS-HFA16TA60C... is a state of the art center tap ultrafast recovery diode. Employing the latest in epitaxial construction and advanced processing techniques it features a superb combination of characteristics which result in performance which is unsurpassed by any rectifier previously available. With basic ratings of 600 V and 8 A per leg continuous current, the VS-HFA16TA60C... is especially well suited for use as the companion diode for IGBTs and MOSFETs. In addition to ultrafast recovery time, the HEXFRED® product line features extremely low values of peak recovery current (I<sub>RRM</sub>) and does not exhibit any tendency to "snap-off" during the to portion of recovery. The HEXFRED features combine to offer designers a rectifier with lower noise and significantly lower switching losses in both the diode and the switching transistor. These HEXFRED advantages can help to significantly reduce snubbing, component count and heatsink sizes. The HEXFRED VS-HFA16TA60C... is ideally suited for applications in power supplies and power conversion systems (such as inverters), motor drives, and many other similar applications where high speed, high efficiency is needed.

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS	
Cathode to anode voltage	V <sub>R</sub>		600	V	
Maximum continuous forward current per leg		T 100 °C	8		
per device	l <sub>F</sub>	T <sub>C</sub> = 100 °C	16	Δ.	
Single pulse forward current	I <sub>FSM</sub>		60	А	
Maximum repetitive forward current	I <sub>FRM</sub>		24		
Maximum payer discination	-	T <sub>C</sub> = 25 °C	36	147	
Maximum power dissipation	$P_{D}$	T <sub>C</sub> = 100 °C	14	W	
Operating junction and storage temperature range	T <sub>J</sub> , T <sub>Stg</sub>		-55 to +150	°C	



# VS-HFA16TA60CPbF, VS-HFA16TA60C-N3

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<b>ELECTRICAL SPECIFICATIONS PER LEG</b> (T <sub>J</sub> = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
Cathode to anode breakdown voltage	V <sub>BR</sub>	I <sub>R</sub> = 100 μA		600	-	-	
Maximum forward voltage		I <sub>F</sub> = 8 A		-	1.4	1.7	V
	V <sub>FM</sub>	I <sub>F</sub> = 16 A	See fig. 1	-	1.7	2.1	
		I <sub>F</sub> = 8 A, T <sub>J</sub> = 125 °C		-	1.4	1.7	
Maximum reverse		$I_{RM}$ $V_R = V_R \text{ rated}$ $V_D = 125 \text{ °C}, V_R = 0.8 \text{ x } V_R \text{ rated}$ See fig. 2		-	0.3	5.0	μA
leakage current	IRM			i	100	500	μΑ
Junction capacitance	C <sub>T</sub>	V <sub>R</sub> = 200 V	See fig. 3	1	10	25	pF
Series inductance	L <sub>S</sub>	Measured lead to lead 5 mm from p	ackage body	-	8.0	-	nH

<b>DYNAMIC RECOVERY CHARACTERISTICS PER LEG</b> (T <sub>J</sub> = 25 °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CO	NDITIONS	MIN.	TYP.	MAX.	UNITS	
	t <sub>rr</sub>	$I_F = 1.0 \text{ A}, dI_F/dt = 200$	A/μs, V <sub>R</sub> = 30 V	-	18	-		
Reverse recovery time See fig. 5 and 10	t <sub>rr1</sub>	T <sub>J</sub> = 25 °C		-	37	55	ns	
See lig. 5 and 10	t <sub>rr2</sub>	T <sub>J</sub> = 125 °C	I <sub>F</sub> = 8.0 A dI <sub>F</sub> /dt = 200 A/μs V <sub>R</sub> = 200 V	-	55	90	]	
Peak recovery current	I <sub>RRM1</sub>	T <sub>J</sub> = 25 °C		-	3.5	5.0	- A - nC	
See fig. 6	I <sub>RRM2</sub>	T <sub>J</sub> = 125 °C		-	4.5	8.0		
Reverse recovery charge	Q <sub>rr1</sub>	T <sub>J</sub> = 25 °C		-	65	138		
See fig. 7	Q <sub>rr2</sub>	T <sub>J</sub> = 125 °C		-	124	360		
Peak rate of fall recovery	dI <sub>(rec)M</sub> /dt1	T <sub>J</sub> = 25 °C		-	240	-	A/µs	
current during t <sub>b</sub> See fig. 8	dI <sub>(rec)M</sub> /dt2	T <sub>J</sub> = 125 °C		-	210	-	γνμS	

THERMAL - MECHANICAL SPECIFICATIONS PER LEG							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Lead temperature	T <sub>lead</sub>	0.063" from case (1.6 mm) for 10 s	-	-	300	°C	
Junction to case, single leg conducting	-		-	-	3.5		
Junction to case, both legs conducting	R <sub>thJC</sub>		-	-	1.75	K/W	
Thermal resistance, junction to ambient	R <sub>thJA</sub>	Typical socket mount	-	-	80	- K/VV	
Thermal resistance, case to heatsink	R <sub>thCS</sub>	Mounting surface, flat, smooth and greased	-	0.5	-		
Maight			-	2.0	-	g	
Weight			-	0.07	-	oz.	
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)	
Marking device		Case style TO-220AB		HFA16TA60C			

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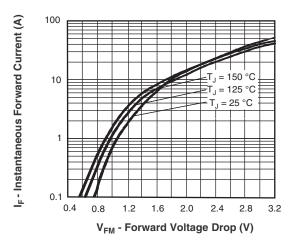


Fig. 1 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current (Per Leg)

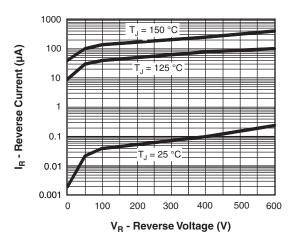


Fig. 2 - Typical Reverse Current vs. Reverse Voltage (Per Leg)

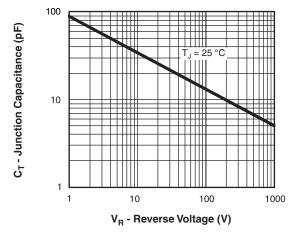


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage (Per Leg)

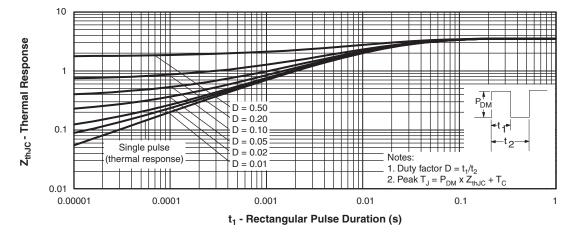


Fig. 4 - Maximum Thermal Impedance  $Z_{\text{thJC}}$  Characteristics (Per Leg)





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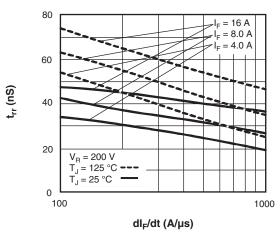


Fig. 5 - Typical Reverse Recovery Time vs. dl<sub>F</sub>/dt (Per Leg)

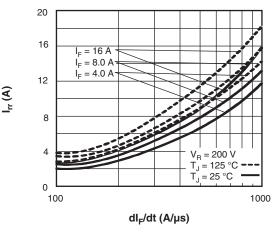


Fig. 6 - Typical Recovery Current vs. dI<sub>F</sub>/dt (Per Leg)

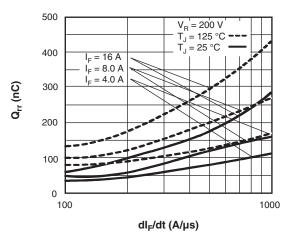


Fig. 7 - Typical Stored Charge vs. dl<sub>F</sub>/dt (Per Leg)

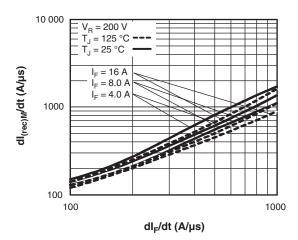
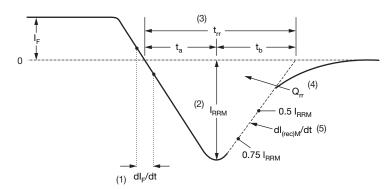


Fig. 8 - Typical dl<sub>(rec)M</sub>/dt vs. dl<sub>F</sub>/dt (Per Leg)



- (1) dl<sub>F</sub>/dt rate of change of current through zero crossing
- (2) I<sub>RRM</sub> peak reverse recovery current
- (3) t<sub>rr</sub> reverse recovery time measured from zero crossing point of negative going I<sub>F</sub> to point where a line passing through 0.75 I<sub>RRM</sub> and 0.50 I<sub>RRM</sub> extrapolated to zero current.
- (4)  $\mathbf{Q}_{rr}$  area under curve defined by  $\mathbf{t}_{rr}$  and  $\mathbf{I}_{RRM}$

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

(5) dI<sub>(rec)M</sub>/dt - peak rate of change of current during t<sub>b</sub> portion of t<sub>rr</sub>

Fig. 9 - Reverse Recovery Waveform and Definitions

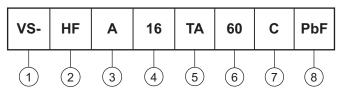
Revision: 04-May-16 4 Document Number: 94058

### VS-HFA16TA60CPbF, VS-HFA16TA60C-N3

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### **ORDERING INFORMATION TABLE**

**Device code** 



1 - Vishay Semiconductors product

2 - HEXFRED® family

3 - Electron irradiated

4 - Current rating (16 = 16 A)

5 - Package:

TA = TO-220AB

6 - Voltage rating (60 = 600 V)

7 - Circuit configuration:

C = common cathode

8 - Environmental digit:

PbF = lead (Pb)-free and RoHS-compliant

-N3 = halogen-free, RoHS-compliant, and totally lead (Pb)-free

ORDERING INFORMATION (Example)							
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION				
VS-HFA16TA60CPbF	50	1000	Antistatic plastic tube				
VS-HFA16TA60C-N3	50	1000	Antistatic plastic tube				

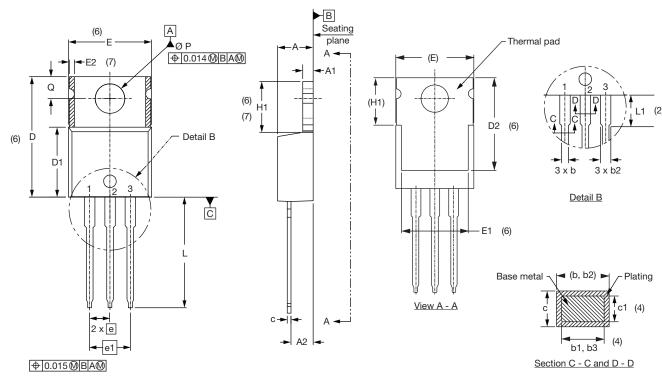
LINKS TO RELATED DOCUMENTS					
Dimensions		www.vishay.com/doc?95222			
Doub according information	TO-220ABPbF	www.vishay.com/doc?95225			
Part marking information	TO-220AB-N3	www.vishay.com/doc?95028			
SPICE model		www.vishay.com/doc?95689			



### Vishay Semiconductors

### **TO-220AB**

### **DIMENSIONS** in millimeters and inches



### Lead assignments

### <u>Diodes</u>

- 1. Anode/open
- 2. Cathode
- 3. Anode

### Conforms to JEDEC outline TO-220AB

SYMBOL	MILLIMETERS		INCHES		NOTES
STWIBOL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.25	4.65	0.167	0.183	
A1	1.14	1.40	0.045	0.055	
A2	2.56	2.92	0.101	0.115	
b	0.69	1.01	0.027	0.040	
b1	0.38	0.97	0.015	0.038	4
b2	1.20	1.73	0.047	0.068	
b3	1.14	1.73	0.045	0.068	4
С	0.36	0.61	0.014	0.024	
c1	0.36	0.56	0.014	0.022	4
D	14.85	15.25	0.585	0.600	3
D1	8.38	9.02	0.330	0.355	
D2	11.68	12.88	0.460	0.507	6

SYMBOL	MILLIN	MILLIMETERS		HES	NOTES
STIVIBOL	MIN.	MAX.	MIN.	MAX.	NOTES
E	10.11	10.51	0.398	0.414	3, 6
E1	6.86	8.89	0.270	0.350	6
E2	-	0.76	-	0.030	7
е	2.41	2.67	0.095	0.105	
e1	4.88	5.28	0.192	0.208	
H1	6.09	6.48	0.240	0.255	6, 7
L	13.52	14.02	0.532	0.552	
L1	3.32	3.82	0.131	0.150	2
ØΡ	3.54	3.73	0.139	0.147	
Q	2.60	3.00	0.102	0.118	
θ	90° to 93° 90° to 93°		o 93°		

#### **Notes**

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension and finish uncontrolled in L1
- (3) Dimension D, D1 and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Dimension b1, b3 and c1 apply to base metal only
- (5) Controlling dimensions: inches
- (6) Thermal pad contour optional within dimensions E, H1, D2 and E1
- $^{(7)}$  Dimensions E2 x H1 define a zone where stamping and singulation irregularities are allowed
- (8) Outline conforms to JEDEC TO-220, except A2 (maximum) and D2 (minimum) where dimensions are derived from the actual package outline

Lead tip



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